

B10H0608N40D

LDMOS 2-stage integrated Doherty MMIC

Rev. 1 — 26 February 2024

AMPLEON

Product data sheet

1. Product profile

1.1 General description

The B10H0608N40D is a dual section 2-stage fully integrated Doherty MMIC solution using Ampleon's state of the art 50 V LDMOS technology. The carrier and peaking device, input splitter, output combiner and pre-match are integrated in each section. This multiband device is perfectly suited as general purpose driver in the frequency range 600 MHz to 800 MHz. Available in a 12 mm × 8 mm LGA outline.

Table 1. Application performance

Typical RF performance at $T_{case} = 25\text{ °C}$; $I_{DQ} = 71\text{ mA}$; $V_{GSq(peaking)} = V_{GSq(carrier)} - 0.55\text{ V}$. Test signal: 1-carrier LTE 20 MHz measured in an Ampleon quad-combined application circuit at $f = 681.5\text{ MHz}$.

Test signal	f	V _{DS}	P _{L(AV)}		G _p	η _D
	(MHz)	(V)	(W)	(dBm)	(dB)	(%)
1-carrier LTE 20 MHz PAR = 7.6 dB	681.5	48	2.512	34	29.9	28.9

1.2 Features and benefits

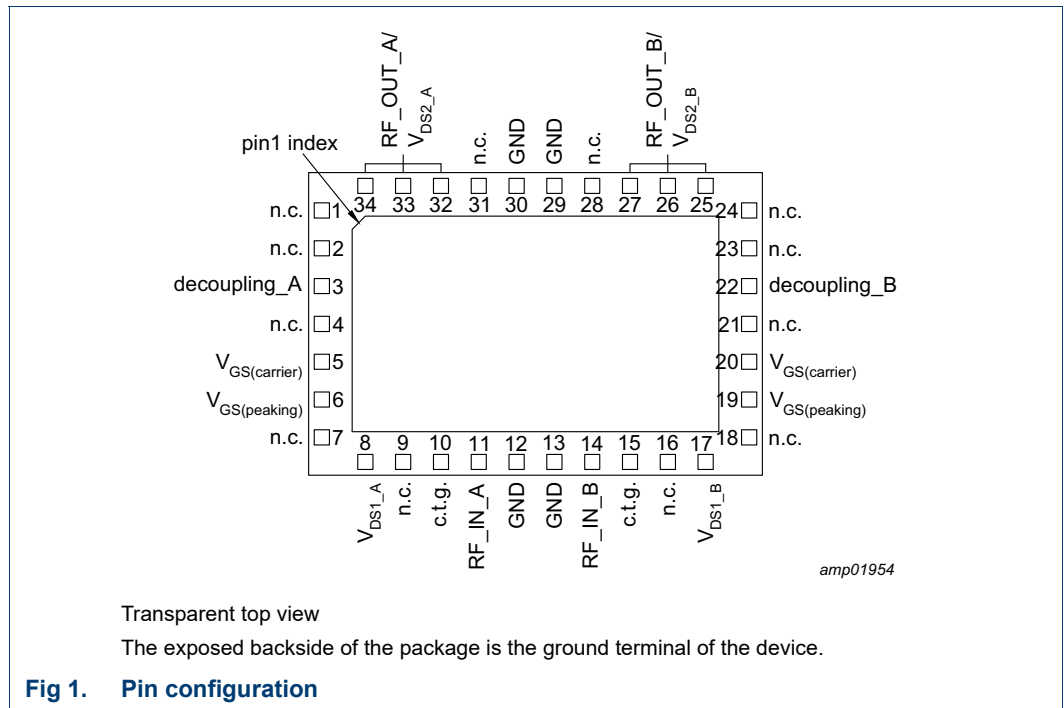
- Integrated input splitter
- Integrated output combiner
- Source impedance 50 Ω
- Pre-matched output
- No output circulator needed thanks to quad-combined configuration
- High linearity
- Designed for large RF and instantaneous bandwidth operation
- Independent control of carrier and peaking bias
- Integrated ESD protection
- High power gain
- For RoHS compliance see the product details on the Ampleon website

1.3 Applications

- 4G/5G macrocell base station driver
- 4G/5G microcell base station

2. Pinning information

2.1 Pinning



2.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
n.c.	1	not connected
n.c.	2	not connected
decoupling_A	3	video-lead for decoupling of section A
n.c.	4	not connected
V _{GS(carrier)}	5	gate-source voltage of carrier [1]
V _{GS(peaking)}	6	gate-source voltage of peaking [2]
n.c.	7	not connected
V _{DS1_A}	8	drain-source voltage of driver stages of section A
n.c.	9	not connected
c.t.g.	10	connect to ground [3]
RF_IN_A	11	RF input of section A
GND	12	ground
GND	13	ground
RF_IN_B	14	RF input of section B
c.t.g.	15	connected to ground [3]
n.c.	16	not connected
V _{DS1_B}	17	drain-source voltage of driver stages of section B

Table 2. Pin description ...continued

Symbol	Pin	Description
n.c.	18	not connected
$V_{GS(peak)}$	19	gate-source voltage of peaking [2]
$V_{GS(carrier)}$	20	gate-source voltage of carrier [1]
n.c.	21	not connected
decoupling_B	22	video-lead for decoupling of section B
n.c.	23	not connected
n.c.	24	not connected
RF_OUT_B/ V_{DS2_B}	25, 26, 27	RF output and drain-source voltage of final stages of section B
n.c.	28	not connected
GND	29	ground
GND	30	ground
n.c.	31	not connected
RF_OUT_A/ V_{DS2_A}	32, 33, 34	RF output and drain-source voltage of final stages of section A

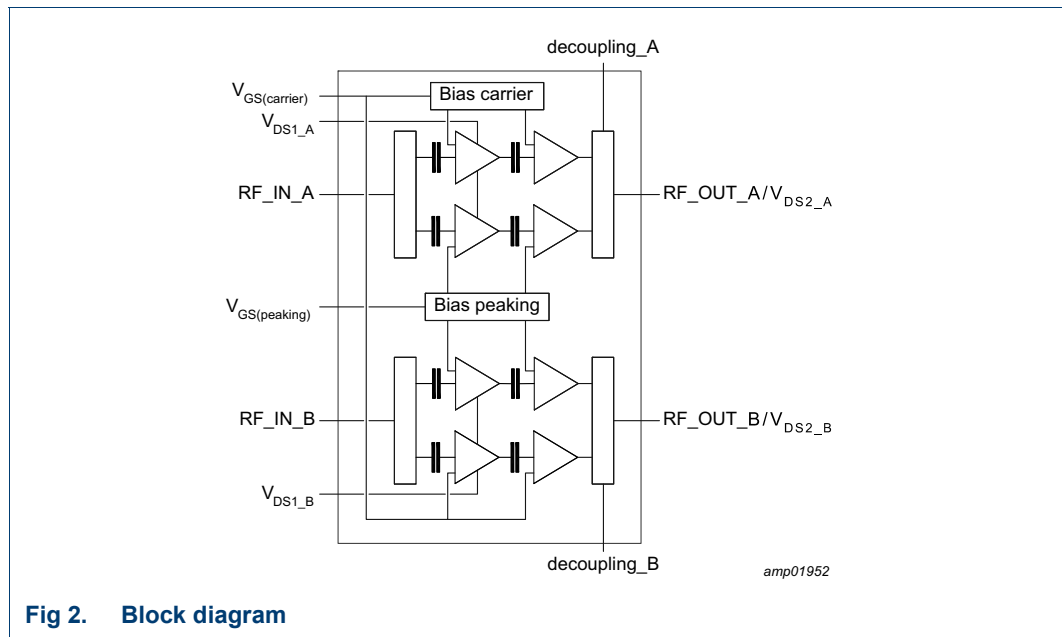
- [1] Pin 5 and pin 20 are internally connected together.
- [2] Pin 6 and pin 19 are internally connected together.
- [3] To be externally connected to ground.

3. Ordering information

Table 3. Ordering information

Package name	Orderable part number	12NC	Packing description	Min. orderable quantity (pieces)
LGA-12x8-34-2	B10H0608N40DX	9349 607 15525	TR13; 3000-fold; 24 mm; dry pack	3000
	B10H0608N40DYZ	9349 607 15535	TR7; 500-fold; 24 mm; dry pack	500

4. Block diagram



5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage		-	110	V
V_{GS}	gate-source voltage		-6	+11	V
T_{stg}	storage temperature		-55	+125	°C
T_j	junction temperature		[1]	225	°C
T_{case}	case temperature		[1]	125	°C

[1] Continuous use at maximum temperature will affect the reliability. For details refer to the online MTF calculator.

6. Recommended operating conditions

Table 5. Operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DD(PA)}$	power amplifier supply voltage	on pins V_{DS1_A} , V_{DS1_B} , V_{DS2_A} , V_{DS2_B} ; $T_{case} = -40\text{ °C}$ to $+120\text{ °C}$	40	52	V
T_{case}	case temperature		-40	+120	°C
$P_{i(M)}$	peak input power	$T_{case} = 25\text{ °C}$; $VSWR = 1 : 1$; $V_{DD(PA)}$ at maximum; pulsed CW power sweep measurement ($\delta = 10\%$; $t_p = 100\text{ }\mu\text{s}$).	-	19	dBm

7. Thermal characteristics

Table 6. Thermal characteristics
Measured for total device.

Symbol	Parameter	Conditions	Value	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	$T_{case} = 90\text{ °C}; P_L = 2.512\text{ W}$	4.1	K/W

[1] When operated with a 1-carrier W-CDMA with PAR = 9.9 dB.

8. Characteristics

Table 7. DC characteristics
 $T_{case} = 25\text{ °C}$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Carrier						
V_{GSq}	gate-source quiescent voltage	$V_{DS} = 48\text{ V}; I_D = 70\text{ mA}$	1.65	2.0	2.65	V
I_{GSS}	gate leakage current	$V_{GS} = 11\text{ V}; V_{DS} = 0\text{ V}$	-	-	120	nA
Peaking						
I_{GSS}	gate leakage current	$V_{GS} = 11\text{ V}; V_{DS} = 0\text{ V}$	-	-	120	nA
Final stages						
I_{DSS}	drain leakage current	$V_{GS} = 0\text{ V}; V_{DS} = 105\text{ V}$	-	-	1.4	μA
Driver stages						
I_{DSS}	drain leakage current	$V_{GS} = 0\text{ V}; V_{DS} = 105\text{ V}$	-	-	1.4	μA

Table 8. RF characteristics

Typical RF performance at $T_{case} = 25\text{ °C}; V_{DS} = 48\text{ V}; I_{Dq} = 70\text{ mA}$ (carrier); $f = 705\text{ MHz}$;
 $V_{GSq(peaking)} = V_{GSq(carrier)} - 0.55\text{ V}; P_{L(AV)} = 34\text{ dBm}$; unless otherwise specified, measured in an Ampleon combined production circuit.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Test signal: pulsed CW [1]						
G_p	power gain	$P_L = 2.51\text{ W}$ (34 dBm)	26	30	34	dB
η_D	drain efficiency	$P_L = 2.51\text{ W}$ (34 dBm)	21	26.5	-	%
		$P_L = P_{L(1dB)}$	45	51.5	-	%
RL_{in}	input return loss	$P_L = 2.51\text{ W}$ (34 dBm)	-	-20	-10	dB
$P_{L(1dB)}$	output power at 1 dB gain compression	$P_L = P_{L(1db)}$	46.2	46.9	-	dBm

[1] Pulsed CW power sweep measurement ($\delta = 10\%$, $t_p = 100\text{ }\mu\text{s}$).

9. Application information

9.1 Typical performance

Table 9. Typical performance

$T_{case} = 25\text{ °C}$; $V_{DS} = 48\text{ V}$; $I_{Dq} = 71\text{ mA}$; $V_{GSq(peak)} = V_{GSq(carrier)} - 0.55\text{ V}$. Test signal: 1-carrier W-CDMA; PAR = 9.9 dB; measured in an Ampleon 617 MHz to 746 MHz frequency band combined application circuit.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$P_{L(1dB)}$	output power at 1 dB gain compression	f = 681.5 MHz [1]	-	47.4	-	dBm
$P_{L(3dB)}$	output power at 3 dB gain compression	f = 681.5 MHz [1]	-	47.8	-	dBm
$\varphi_{s21}/\varphi_{s21(norm)}$	normalized phase response	at 1 dB compression point; f = 681.5 MHz [2]	-	-8.7	-	°
η_D	drain efficiency	13.8 dB OBO ($P_{L(AV)} = 34\text{ dBm}$); f = 681.5 MHz	-	27.2	-	%
G_p	power gain	$P_{L(AV)} = 34\text{ dBm}$; f = 681.5 MHz	-	29.9	-	dB
B_{video}	video bandwidth	$P_{L(AV)} = 37.5\text{ dBm}$ set to obtain IMD3 = -30 dBc; 2-tone CW; f = 681.5 MHz	-	161	-	MHz
G_{flat}	gain flatness	$P_{L(AV)} = 34\text{ dBm}$; f = 617 MHz to 746 MHz	-	1	-	dB
$ACPR_{5M}$	adjacent channel power ratio (5 MHz)	$P_{L(AV)} = 34\text{ dBm}$; f = 681.5 MHz	-	-40.2	-	dBc
$\Delta G/\Delta T$	gain variation with temperature	f = 681.5 MHz [3]	-	0.05	-	dB/°C
K	Rollett stability factor	$T_{case} = -40\text{ °C}$; f = 0.1 GHz to 3 GHz [3]	-	>1	-	

[1] Pulsed CW power sweep measurement ($t_p = 100\text{ }\mu\text{s}$; $\delta = 10\text{ %}$).

[2] 25 ms CW power sweep measurement.

[3] Small-signal s-parameters.

9.2 Component layout

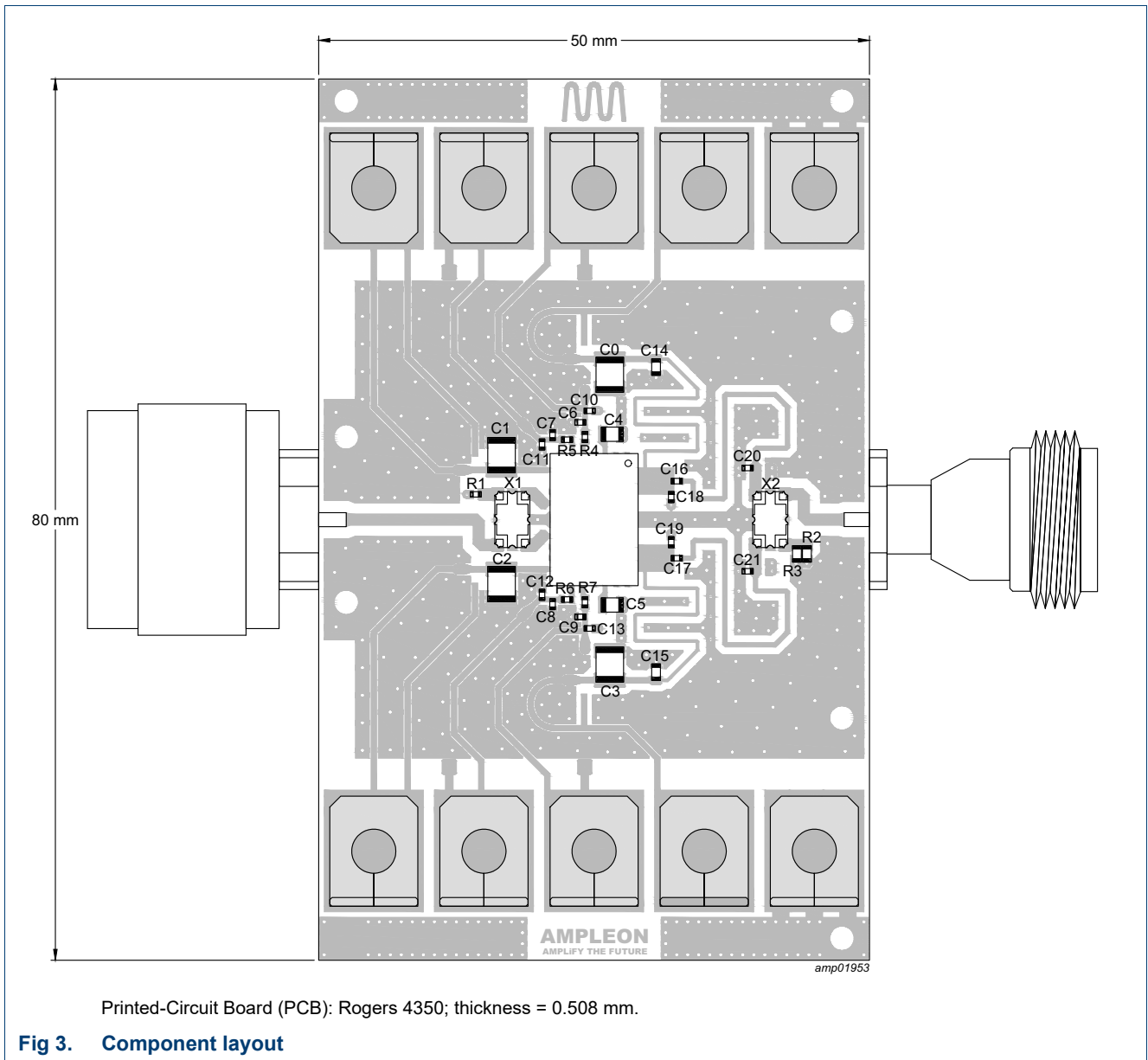


Table 10. Demo test circuit list of components

See Figure 3 for component layout.

Component	Description	Value	Remarks
C0, C1, C2, C3	multilayer ceramic chip capacitor	10 μ F, 100 V	Murata: GRM32EC72A106KE05K
C4, C5	multilayer ceramic chip capacitor	1 μ F, 100 V	Murata: CGA4J3X7S2A105K125AB
C6, C7, C8, C9	multilayer ceramic chip capacitor	100 nF, 6.3 V	Murata: GRM155R70J104KA01D
C10, C11, C12, C13	multilayer ceramic chip capacitor	4.7 μ F, 6.3 V	Murata: GCJ188C70J475ME02D
C14, C15	multilayer ceramic chip capacitor	68 pF, 250 V	Murata: GQM1875C2E680FB12D
C16, C17	multilayer ceramic chip capacitor	13 pF, 200 V	Murata: GQM1555C2D130GB01D
C18, C19	multilayer ceramic chip capacitor	3.3 pF, 200 V	Murata: GQM1555C2D3R3BB01D

Table 10. Demo test circuit list of components ...continued
See [Figure 3](#) for component layout.

Component	Description	Value	Remarks
C20, C21	multilayer ceramic chip capacitor	2.7 pF, 200 V	Murata: GQM1555C2D2R7BB01D
R1	resistor	50 Ω, ±1 %, 100 mW	Vishay: FC0402E50R0BST1
R2, R3	resistor	100 Ω, ±1 %, 200 mW	Multicomp Pro: MP001293
R4, R5, R6, R7	resistor	51 Ω, ±1 %, 100 mW	Multicomp Pro: MP000480
X1, X2	hybrid coupler	600 MHz – 1000 MHz, 25 W	Anaren: X3C07F1-03S
J1	N coaxial panel connector male		Radiall: R161.438.200
J2	N coaxial panel connector female		Huber & Suhner: 23_N-50-0-16/133_NE

9.3 Recommendations

It is mandatory to use the B10H0608N40D in quad-combined configuration.

9.4 Ruggedness in a Doherty operation

9.4.1 Output mismatch ruggedness

The B10H0608N40D is capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions: $V_{DS} = 52$ V; $I_{Dq} = 70$ mA (carrier); $V_{GSq(peak)} = V_{GSq(carrier)} - 0.55$ V; P_i corresponding to $P_{L(1dB)} - 9$ dB under $Z_S = 50$ Ω load; $f = 681.5$ MHz (1-carrier W-CDMA); $T_{case} = 25$ °C.

9.4.2 Wideband noise ruggedness

The B10H0608N40D is capable of withstanding an AWGN (Additive White Gaussian Noise) with 11.2 dB PAR, OBW (Occupied BandWidth) of 900 MHz, under the following conditions: $V_{DS} = 52$ V; $I_{Dq} = 70$ mA (carrier); $V_{GSq(peak)} = V_{GSq(carrier)} - 0.55$ V; 3 dB P_{out} overdrive from $P_{L(AV)} = 34$ dBm; $f = 681.5$ MHz; $T_{case} = 25$ °C.

9.5 Impedance information

Table 11. Typical impedance for optimum Doherty operation

Measured load-pull data per section; test signal: pulsed CW; $T_{case} = 25$ °C; $V_{DS} = 48$ V; $I_{Dq} = 35$ mA (carrier); $V_{GSq(peak)} = V_{GSq(carrier)} - 0.55$ V; $t_p = 100$ μs; $\delta = 10$ %.

f (MHz)	tuned for optimum Doherty operation				
	Z_L (Ω)	$P_{L(1dB)}$ (dBm)	$G_{p(max)}$ (dB)	η_{add} [1] (%)	η_{add} [2] (%)
617	34.91 + 2.41j	44.61	31.76	26.97	58.54
652	33.95 + 2.12j	44.58	31.76	28.97	57.61
685	33.46 + 2.36j	44.36	31.95	28.92	56.43
729	33.50 + 3.14j	44.13	31.79	27.43	52.91
746	33.79 + 3.58j	43.91	32.04	26.52	50.37

[1] At 31 dBm.

[2] At $P_{L(1dB)}$.

10. Package outline

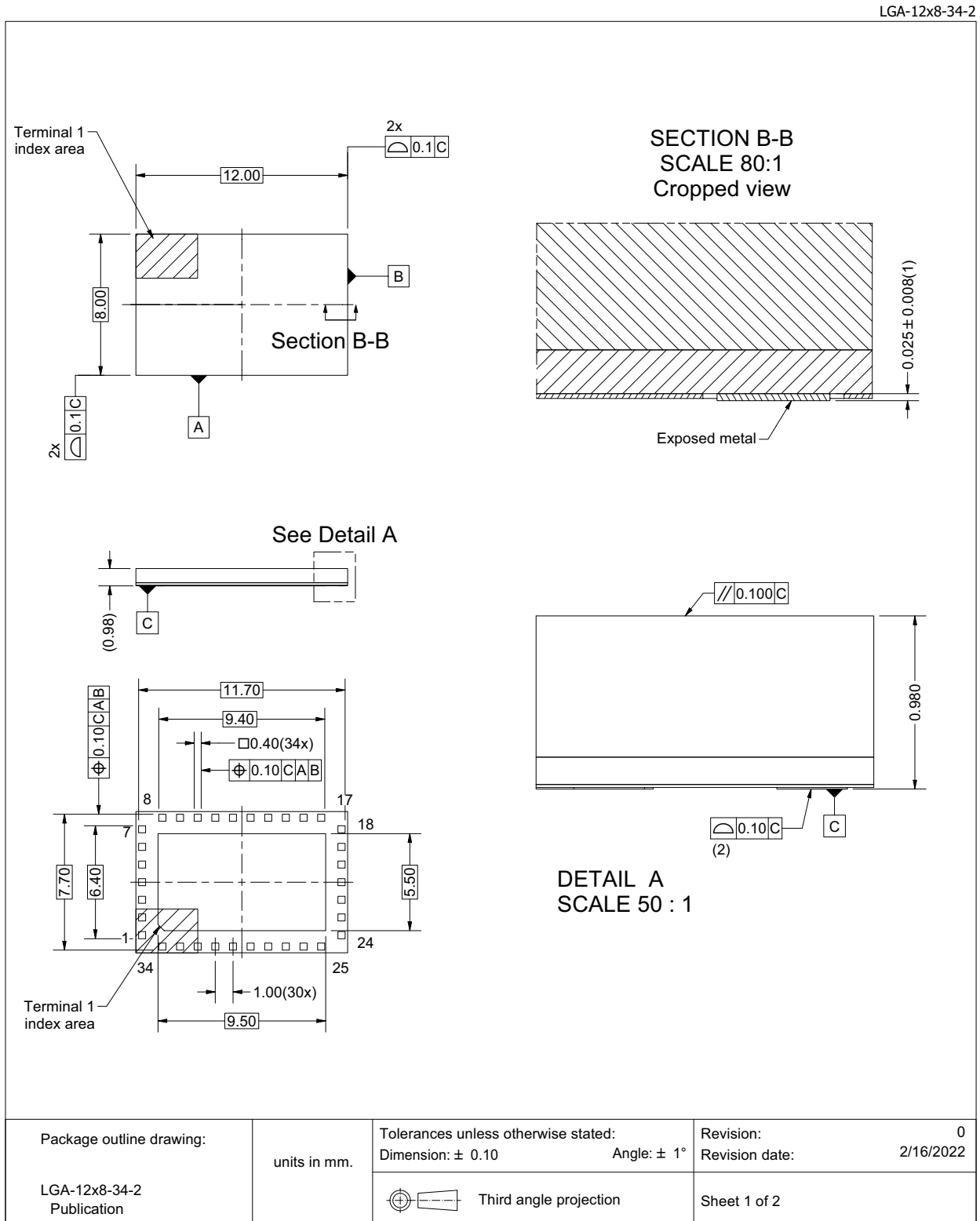


Fig 4. Package outline LGA-12x8-34-2 (sheet 1 of 2)

11. Handling information

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

Table 12. ESD sensitivity

ESD model	Class
Charged Device Model (CDM); According to ANSI/ESDA/JEDEC standard JS-002	C1 [1]
Human Body Model (HBM); According to ANSI/ESDA/JEDEC standard JS-001	1C [2]

[1] CDM classification C1 is granted to any part that passes after exposure to an ESD pulse of 250 V.

[2] HBM classification 1C is granted to any part that passes after exposure to an ESD pulse of 1000 V.

12. Abbreviations

Table 13. Abbreviations

Acronym	Description
4G	Fourth Generation
5G	Fifth Generation
CW	Continuous Wave
ESD	ElectroStatic Discharge
LDMOS	Laterally Diffused Metal Oxide Semiconductor
LTE	Long Term Evolution
MMIC	Monolithic Microwave Integrated Circuit
MTF	Median Time to Failure
OBO	Output Back Off
PAR	Peak-to-Average power Ratio
RoHS	Restriction of Hazardous Substances
VSWR	Voltage Standing Wave Ratio
W-CDMA	Wideband Code Division Multiple Access

13. Revision history

Table 14. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
B10H0608N40D v.1	20240226	Product data sheet	-	-

14. Legal information

14.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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